

# PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Markus Brunnbauer	01/19/2007
RECEIVING PARTY DATA	
Name:	Infineon Technologies AG
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	11622773
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ATTORNEY DOCKET NUMBER:	3002.0069C
NAME OF SUBMITTER:	Patrick J. Finnann
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OP \$40.00 11622773

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PATENT  
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REF NO. FIN 837  
O.C. REF NO. 3002.0069C

### ASSIGNMENT

For good and valuable consideration, I, Markus Brunnbauer, a citizen of Germany, residing at Auf den Hoehen 8, 93138 Lappersdorf, Germany, hereinafter individually or collectively referred to as "Assignor";

Hereby sell, assign and transfer to **Infineon Technologies AG**, a corporation organized and existing under the laws of Germany, having its principal place of business at St.-Martin-Str. 53, 81669 Munich, Germany, hereinafter "Assignee", its successors, assigns and legal representatives, the entire right, title and interest in and for the United States and all foreign countries, in and to any and all improvements which are disclosed in the application for United States Letters Patent, which has been executed by the undersigned and

filed on January 12, 2007 as US. Application Serial No. 11/622,773,

entitled: **Semiconductor Module Comprising Semiconductor Chips and Method for Producing the Same**

and in and to said application and all divisional, continuing, substitute, renewal, reissue, and all other applications for Letters Patent which have been or shall be filed in the United States and all foreign countries on any of said improvements; and in and to all original and reissued patents which have been or shall be filed in the United States and all foreign countries on said improvements;

Agree that said Assignee may apply for and receive Letters Patent for said improvements in its own name; and that, when requested, without charge to but at the expense of said Assignee, its successors, assigns and legal representatives, to carry out in good faith the intent and purpose of this assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all said improvements; execute all rightful oaths, assignments, powers of attorney and other papers; communicate to said Assignee, its successors, assigns, and legal representatives, all facts known to the undersigned relating to said improvements and the history thereof; and generally do everything possible which said Assignee, its successors, assigns or legal representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns and legal representatives; and

Covenant with said Assignee, its successors, assigns and legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

SIGNATURE: 

Markus Brunnbauer

DATE: 12.1.07